

MT3288/B

N-Channel 80V/200A Power MOSFET

Features

- $R_{DS(on)} = 2.9\text{ m}\Omega$ at $V_{GS} = 10\text{V}$, $I_D = 100\text{A}$
- Fast Switching Speed
- Low Gate Charge
- 100% avalanche tested

General Description

This N-Channel MOSFET is produced using MOS-TECH Semiconductor's advanced PowerTrench process that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

Applications

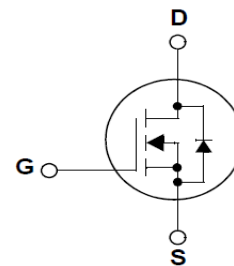
- DC-DC primary bridge
- DC-DC Synchronous rectification
- Power Management for Inverter Systems



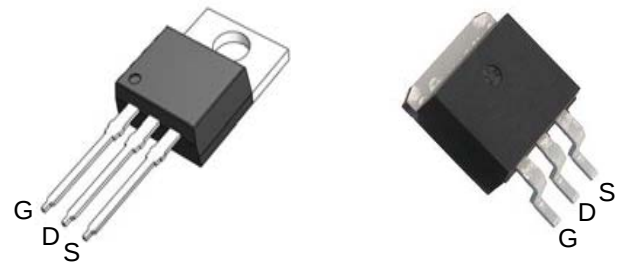
MT Semiconductor®

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Simplified Schematic



MARKING DIAGRAM & PIN ASSIGNMENT



		Package Code MT3288: TO-220FB-3L MT3288B: TO-263-2L	
Date Code PYWWM		Lot NO XX	

Absolute Maximum Ratings

Symbol	Parameter		Rating	Unit
Common Ratings (T _C =25°C Unless Otherwise Noted)				
V _{DSS}	Drain-Source Voltage		80	V
V _{GSS}	Gate-Source Voltage		±25	
T _J	Maximum Junction Temperature		150	°C
T _{STG}	Storage Temperature Range		-55 to 150	°C
I _S	Diode Continuous Forward Current	T _C =25°C	200	A

Mounted on Large Heat Sink

I _{DM}	Pulsed Drain Current *	T _C =25°C	790**	A
I _D	Continuous Drain Current	T _C =25°C	200	A
		T _C =100°C	144	
P _D	Maximum Power Dissipation	T _C =25°C	345	W
		T _C =100°C	173	
R _{θJC}	Thermal Resistance-Junction to Case		0.43	°C/W
R _{θJA}	Thermal Resistance-Junction to Ambient		62.5	
Avalanche Ratings				
E _{AS}	Avalanche Energy, Single Pulsed	L=0.5mH	1496***	mJ

Note : * Repetitive rating ; pulse width limited by junction temperature

** Drain current is limited by junction temperature

*** $V_D=64\text{V}$

Electrical Characteristics ($T_C = 25^{\circ}\text{C}$ Unless Otherwise Noted)

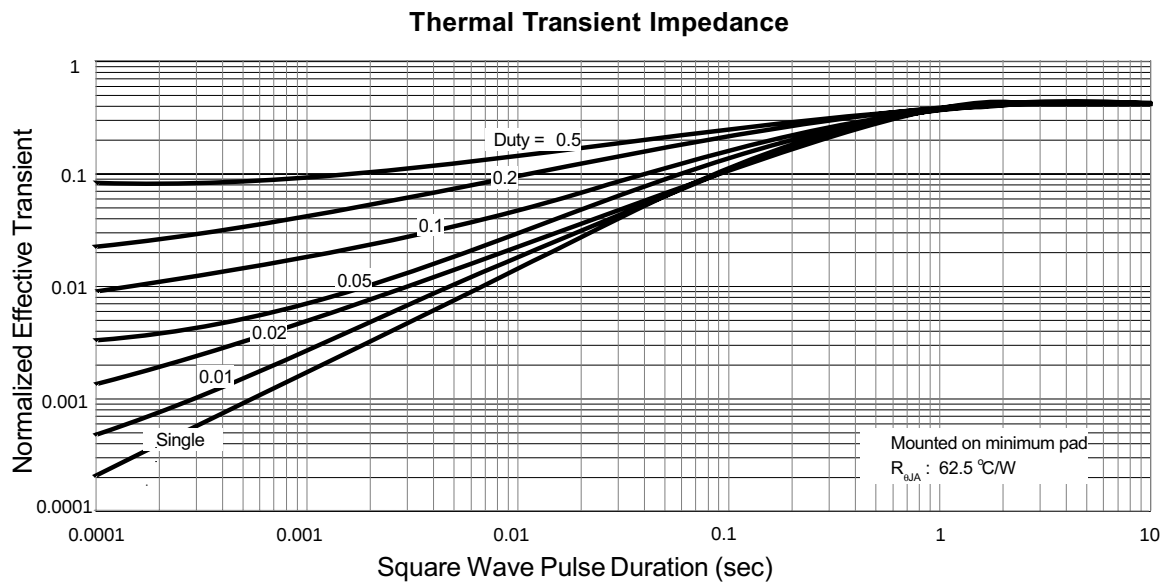
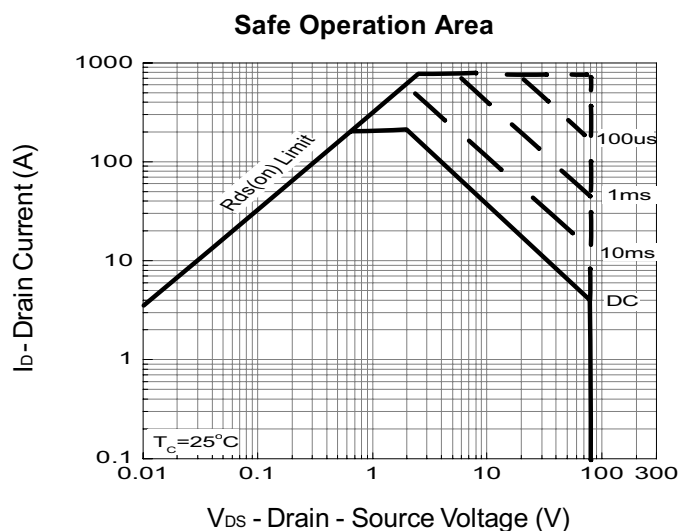
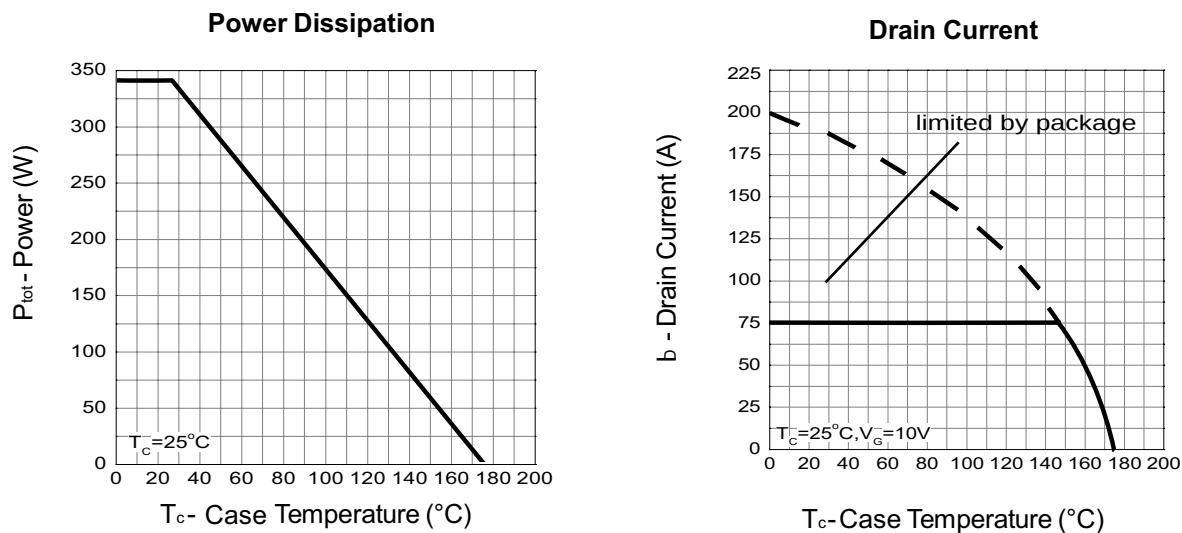
Symbol	Parameter	Test Conditions				Unit
			Min.	Typ.	Max.	
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =250μA	80	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =80V, V _{GS} =0V	-	-	1	μA
		T _J =85°C	-	-	10	
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =250μA	2.0	3.0	4.0	V
I _{GSS}	Gate Leakage Current	V _{GS} =±25V, V _{DS} =0V	-	-	±100	nA
R _{DS(ON)} *	Drain-Source On-state Resistance	V _{GS} =10V, I _{DS} =100A	-	2.9	3.5	mΩ
Diode Characteristics						
V _{SD} *	Diode Forward Voltage	I _{SD} =100A, V _{GS} =0V	-	0.8	1.2	V
t _{rr}	Reverse Recovery Time	I _{SD} =100A, dI _{SD} /dt=100A/μs	-	30	-	ns
Q _{rr}	Reverse Recovery Charge		-	52	-	nC

Electrical Characteristics (Cont.) ($T_C = 25^\circ\text{C}$ Unless Otherwise Noted)

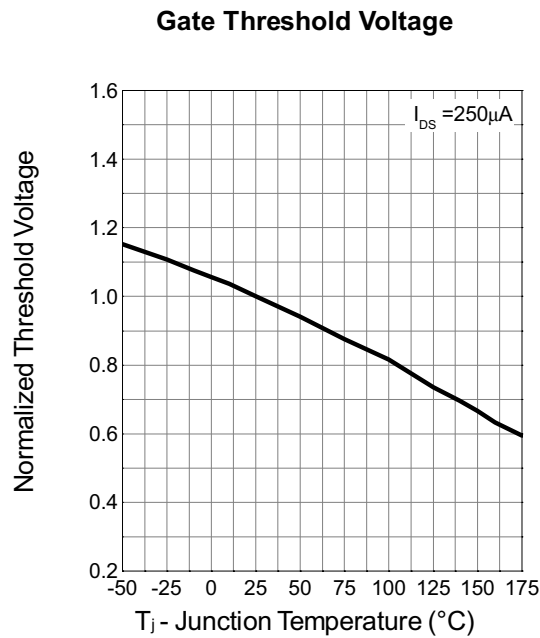
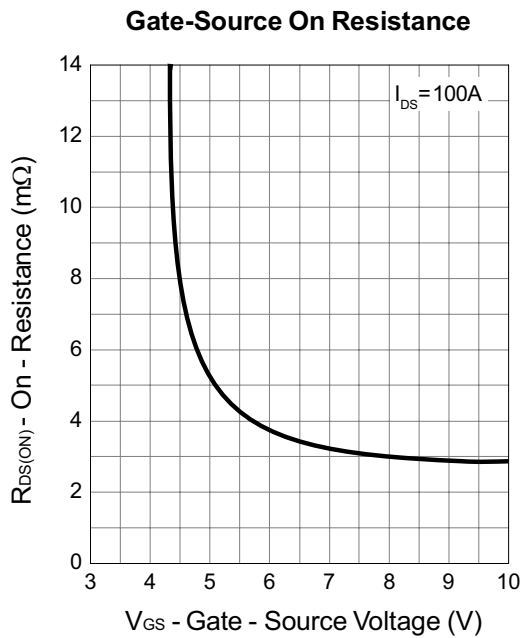
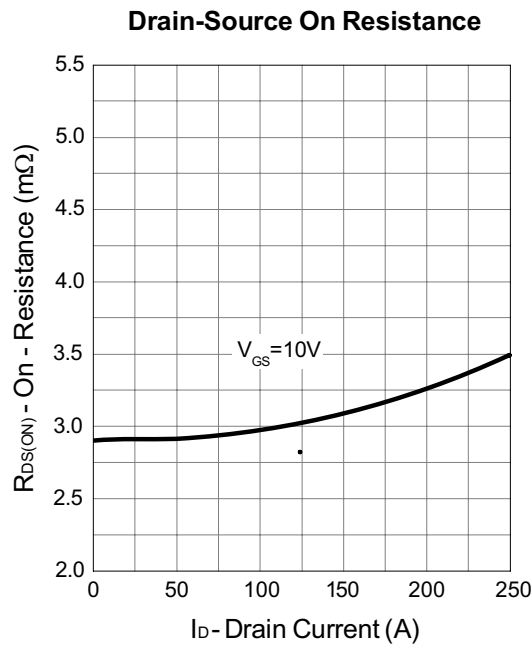
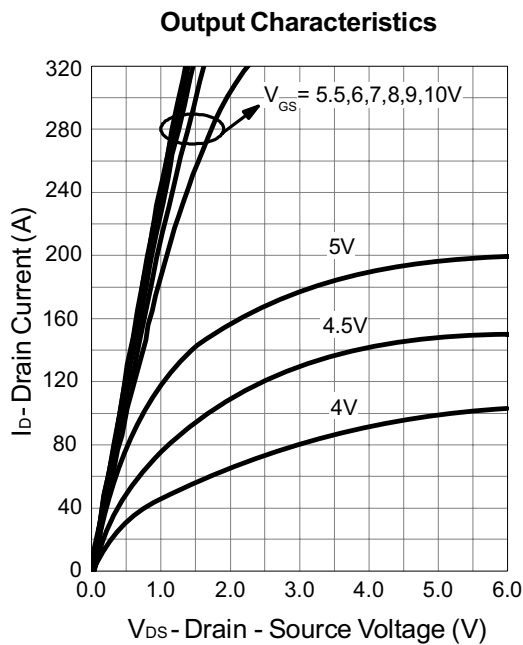
Symbol	Parameter	Test Conditions				Unit
			Min.	Typ.	Max.	
Dynamic Characteristics						
R _G	Gate Resistance	V _{GS} =0V, V _{DS} =0V, F=1MHz	-	3.2	-	Ω
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =25V, Frequency=1.0MHz	-	8154	-	pF
C _{oss}	Output Capacitance		-	1029	-	
C _{rss}	Reverse Transfer Capacitance		-	650	-	
t _{d(ON)}	Turn-on Delay Time	V _{DD} =40V, R _G =6 Ω, I _{DS} =100A, V _{GS} =10V,	-	28	-	ns
T _r	Turn-on Rise Time		-	18	-	
t _{d(OFF)}	Turn-off Delay Time		-	42	-	
T _f	Turn-off Fall Time		-	54	-	
Gate Charge Characteristics						
Q _g	Total Gate Charge	V _{DS} =64V, V _{GS} =10V, I _{DS} =100A	-	197	-	nC
Q _{gs}	Gate-Source Charge		-	31	-	
Q _{gd}	Gate-Drain Charge		-	75	-	

Note * : Pulse test ; pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.

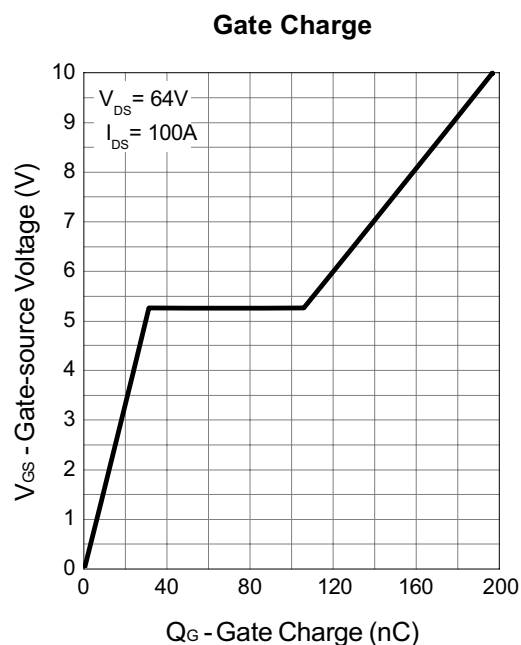
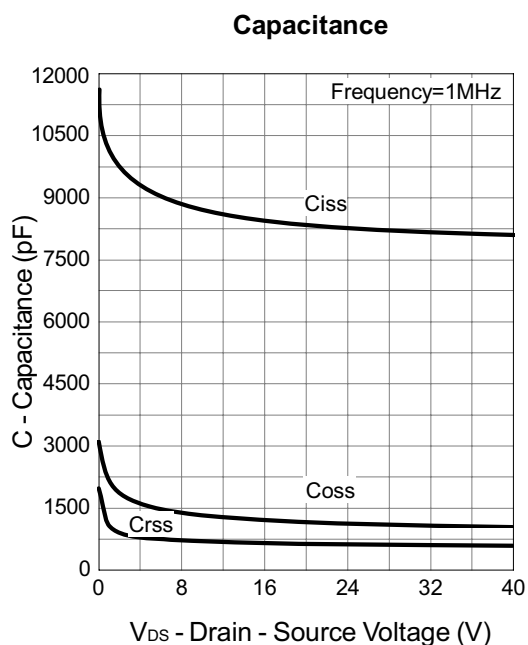
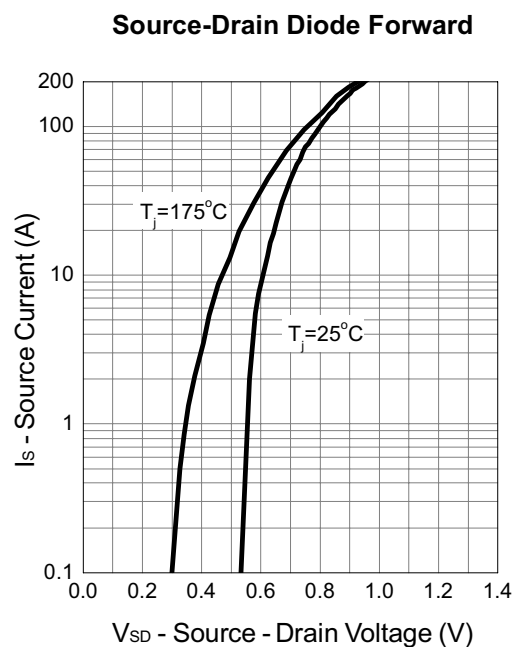
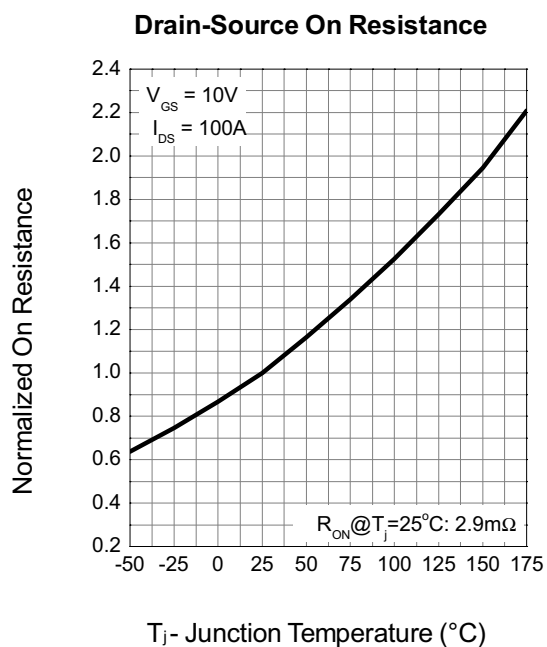
Typical Operating Characteristics



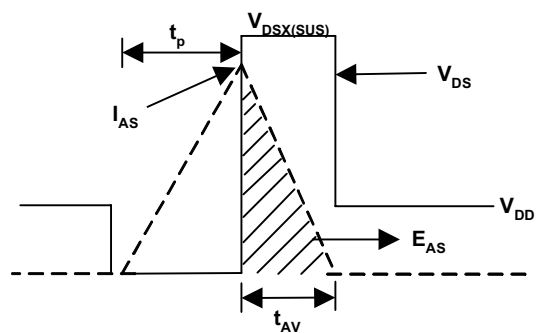
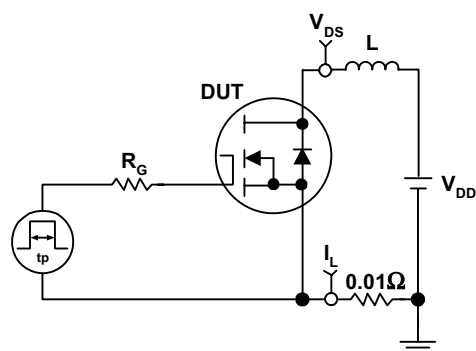
Typical Operating Characteristics (Cont.)



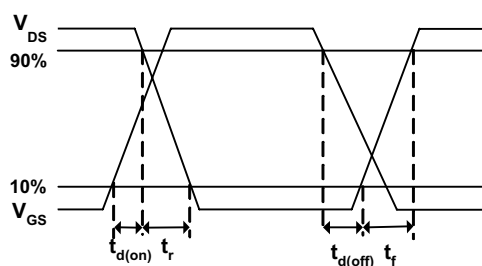
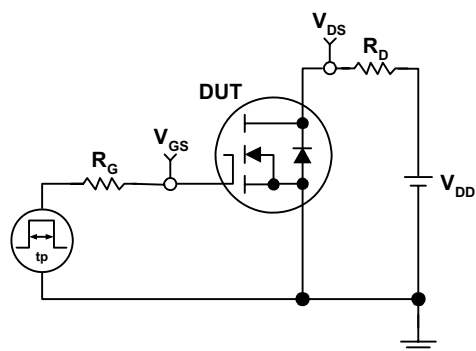
Typical Operating Characteristics (Cont.)



Avalanche Test Circuit and Waveforms

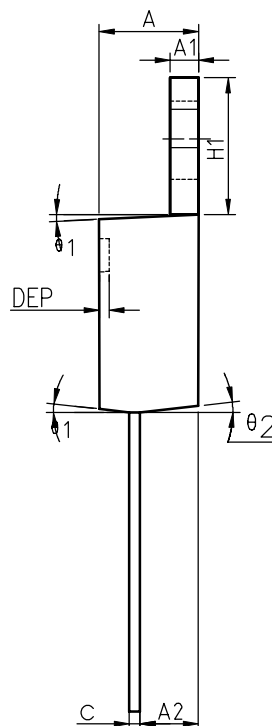
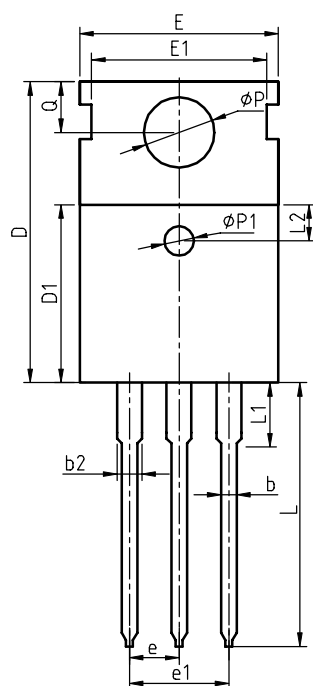


Avalanche Test Circuit and Waveforms



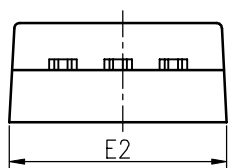
Package Information

TO-220FB-3L

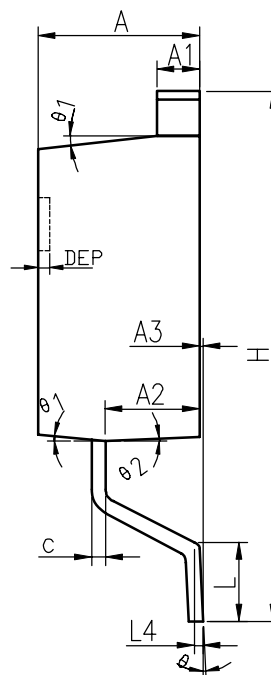
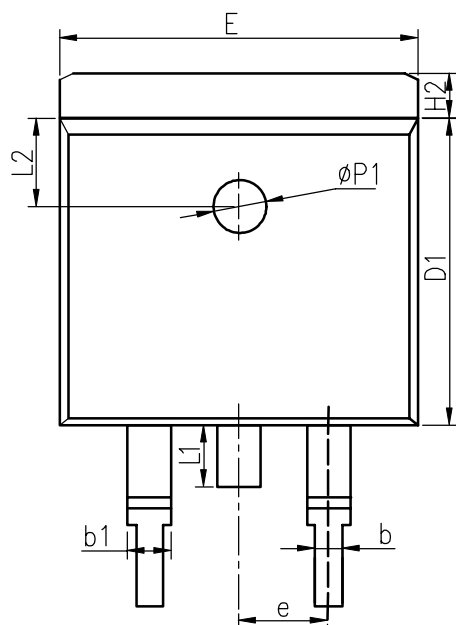


COMMON DIMENSIONS

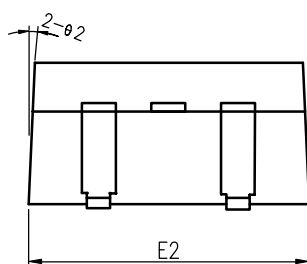
SYMBOL	MIN	NOM	MAX	MIN	NOM	MAX
A	4.40	4.57	4.70	0.173	0.180	0.185
A1	1.27	1.30	1.33	0.050	0.051	0.052
A2	2.35	2.40	2.50	0.093	0.094	0.098
b	0.77	0.80	0.90	0.030	0.031	0.035
b2	1.17	1.27	1.36	0.046	0.050	0.054
c	0.48	0.50	0.56	0.019	0.020	0.022
D	15.40	15.60	15.80	0.606	0.614	0.622
D1	9.00	9.10	9.20	0.354	0.358	0.362
DEP	0.05	0.10	0.20	0.002	0.004	0.008
E	9.80	10.00	10.20	0.386	0.394	0.402
E1	—	8.70	—	—	0.343	—
E2	9.80	10.00	10.20	0.386	0.394	0.402
e	—	2.54	BSC	—	0.100	BSC
e1	—	5.08	BSC	—	0.200	BSC
H1	6.40	6.50	6.60	0.252	0.256	0.260
L	12.75	13.50	13.65	0.502	0.531	0.537
L1	—	3.10	3.30	—	0.122	0.130
L2	—	2.50	REF	—	0.098	REF
P	3.50	3.60	3.63	0.138	0.142	0.143
P1	3.50	3.60	3.63	0.138	0.142	0.143
Q	2.73	2.80	2.87	0.107	0.110	0.113
$\theta 1$	5°	7°	9°	5°	7°	9°
$\theta 2$	1°	3°	5°	1°	3°	5°
$\theta 3$	1°	3°	5°	1°	3°	5°



TO-263-2L



COMMON DIMENSIONS



SYMBOL	MM			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX
A	4.40	4.57	4.70	0.173	0.180	0.185
A1	1.22	1.27	1.32	0.048	0.050	0.052
A2	2.59	2.69	2.79	0.102	0.106	0.110
A3	0.00	0.10	0.20	0.000	0.004	0.008
b	0.77	0.813	0.90	0.030	0.032	0.035
b1	1.20	1.270	1.36	0.047	0.050	0.054
c	0.34	0.381	0.47	0.013	0.015	0.019
D1	8.60	8.70	8.80	0.339	0.343	0.346
E	10.00	10.16	10.26	0.394	0.400	0.404
E2	10.00	10.10	10.20	0.394	0.398	0.402
e	2.54 BSC			0.100 BSC		
H	14.70	15.10	15.50	0.579	0.594	0.610
H2	1.17	1.27	1.40	0.046	0.050	0.055
L	2.00	2.30	2.60	0.079	0.091	0.102
L1	1.45	1.55	1.70	0.057	0.061	0.067
L2	2.50 REF			0.098 REF		
L4	0.25 BSC			0.010 BSC		
	0°	5°	8°	0°	5°	8°
1	5°	7°	9°	5°	7°	9°
2	1°	3°	5°	1°	3°	5°
ΦP1	1.40	1.50	1.60	0.055	0.059	0.063
DEP	0.05	0.10	0.20	0.002	0.004	0.008

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